

## Sn63/Pb37 RA Solder Wires

4880–4888 solder wires use the eutectic tin-lead alloy ratio, with a RA-like flux core. They have a low-melting temperature with a sharp melting/solidification point.

They achieve a consistent solder and flux percentage due to our state-of-the-art extrusion wire-drawing machine, which continuously monitors the wire to prevent voids and ensure consistency, providing a top-grade solder wire.

## Features & Benefits

Eutectic alloy (liquidus=solidus temperature)

Alloy exceeds J-STD-006C, meets J-STD004B and ASTM B 32 purity requirements

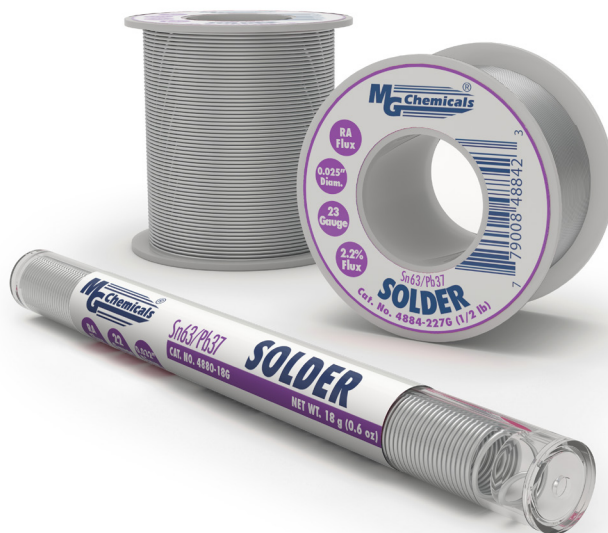
Rosin-activated flux

Fast wetting and flowing

Non-corrosive and non-conductive residue

## Storage and Handling

Store between 18 and 25 °C in a dry area, away from sunlight (see SDS).



## Available Packaging

Part #	Packaging	Gauge	Diameter	Net Wt.
4880-18G	Pocket Pack	21	0.032"	18 g
4884-227G	Spool	23	0.025"	227 g
4884-454G	Spool	23	0.025"	454 g
4885-227G	Spool	21	0.032"	227 g
4885-454G	Spool	21	0.032"	454 g
4886-227G	Spool	19	0.040"	227 g
4886-454G	Spool	19	0.040"	227 g
4887-227G	Spool	18	0.050"	227 g
4887-454G	Spool	18	0.050"	454 g
4888-227G	Spool	16	0.062"	227 g
4888-454G	Spool	16	0.062"	454 g

## Properties

Flux Classification	ROM1 RA	J-STD-004B, MIL-F-14256F
Flux Type	Rosin	J-STD-004B
Flux Activity	Moderate	J-STD-004B
Solder Flux Color	Amber	—
Corrosion Test	Pass	IPC-TM-650 2.6.15
Surface Insulation Resistance (SIR)	$>1.0 \times 10^9 \Omega$	IPC-TM-650 2.6.3.7
Acid Number (mgKOH/g sample)	150–160	IPC-TM-650 2.3.13
Halides (by weight)	0.5–2.0 %	IPC-TM-650 2.3.35
Silver Chromate (Cl <sup>-</sup> + Br)	Detection	—
Softening Point of Flux Residue	80 °C	—
Shelf Life	10 y	—

**Disclaimer:** This information is believed to be accurate. It is intended for professional end-users who have the skills required to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.